

Bill of Materials
TI Designs

TIDM-TM4CSTEPPER MOTOR

DRV8833 EVM

Item	Ref	Qty	Description	Mfg	Part Number
1	C1	1	Capacitor	TDK Corporation	C2012X5R1C106M
2	C2, C4	2	Capacitor	TDK Corporation	C1608X5R0J225K
3	C3, C5	2	Capacitor	Murata Electronics North Americ, Murata Electronics North America	GRM188R71E103KA01D
4	C6	1	Capacitor	TDK Corporation	C1608Y5V1C105Z
5	C9	1	Capacitor	TDK Corporation	C1608X7R1E104K
6	C11	1	Polarized Capacitor (Radial)	Nichicon	RNE1C101MDS1PX
7	D1	1	LED RED CLEAR 1206 SMD	Stanley Electric & Co	HBR1105W-TR
8	J1	1	Header, 8-Pin	Phoenix Contact	1945151
9	J2	1	Header, 4-Pin	Phoenix Contact	1945119
10	JP1, JP2, JP3, JP4	4	Three Pin Jumper	Phoenix Contact	1945106
11	JP5, JP6	2	Two Pin Jumper	Phoenix Contact	1945096
12	R5, R6	2	Resistor	Vishay/Dale (VA)	WSL2512R1500FEA
13	R9	1	Resistor	Stackpole Electronics Inc	RNCP0805FTD499R
14	REG1	1	VoltageRegulator	Texas Instruments	LP2985-50DBVR
15	S1, S2, S3, S4	4	SPDT ON OFF ON	NKK Switches	B13AP
16	TP1, TP2, TP3, TP4, TP6, TP7, TP8, TP10, TP11, TP13, TP14, TP15, TP16, TP17	14	Glass Beaded Test Point	Kobiconn	151-101-RC
17	TP5, TP9	2	Glass Beaded Test Point	Kobiconn	151-103-RC
18	TP12	1	Glass Beaded Test Point	Kobiconn	151-107-RC
19	U1	1	Dual H Bridge	Texas Instruments	DRV8833PWP

Item	Ref	Qty	Description	Mfg	Part Number
1	C1 C2 C7 C12, C14	5	Capacitor, 0402, X5R, 10V, Low ESR	Johanson Dielectrics Inc	100R07X105KV4T
2	C25 C26 C31 C32	4	Capacitor, 10pF, 50V, 5%, NPO/COG, 0402	Murata	GRM1555C1H100JZ01D
3	C28 C29	2	Capacitor, 24pF, 50V, 5%, NPO/COG, 0402	TDK	C1005C0G1H240J
4	C3 C5 C8 C15 C18 C19 C21	7	Capacitor, 0.01uF 25V, 10% 0402 X7R	Taiyo Yuden	TMK105B7103KV-F
5	C4 C6 C10 C11 C17 C20 C23 C24	8	Capacitor, 0.1uF 16V, 10% 0402 X7R	Taiyo Yuden	EMK105B7104KV-F
6	C9 C22	2	Capacitor, 2.2uF, 16V, 10%, 0603, X5R	Murata	GRM188R61C225KE15D
7	D1	1	LED, Tri-Color RGB, 0404 SMD Common Anode	Everlight	18-038/RSGHBHC1-S02/2T
8	D4	1	LED, Green 565nm, Clear 0805 SMD	Lite-On	LTST-C171GKT
				Lite-On	LTST-C171GKT
9	H24	1	Header, 1x2, 0.100, T-Hole, Vertical Unshrouded, 0.220 Mate	FCI	68001-102HLF
				Anyone	1x2-head
10	H25	1	Jumper, 0.100, Gold, Black, Closed	Sullins	SPC02SYAN
11	J1 J3	2	Header, 2x10, T-Hole Vertical unshrouded stacking	Samtec	SSW-110-23-S-D
12	J11	1		Hirose	ZX62-B-5PA
13	J2 J4	2	Header, 2x10, 0.100, SMT, Horizontal Unshrouded, 0.230 Mate	Samtec	TSM-110-01-S-DH-A-P-TR
				4UCON	10995
				Major League Electronics	TSHSM-110-D-02-T-H-AP-TR-P-LF
14	J9	1	Connector, USB micro AB Receptacle SMD	Hirose	ZX62-AB-5PA(11)
				Hirose	ZX62-AB-5PA
15	Q1 Q2 Q3	3	NPN SC70 pre-biased	Diodes Inc	DTC114EET1G
16	R1 R2 R9 R10 R11 R12 R13 R14 R16, R20 R26	11	Resistor, 0 OHM 1/10W 0603 SMD	Panasonic	ERJ-3GEY0R00V
17	R18 R19 R21 R22 R23 R28	6	Resistor, 10k ohm, 1/10W, 5%, 0402 Thick Film	Yageo	RC0402FR-0710KL
18	R3 R4 R5 R8 R27	5	Resistor, 330 ohm, 1/10W, 5%, 0402	Yageo	RC0402FR-07330RL
19	R31	1	Resistor, 1M Ohm 1/10W, 5%, 0402	Rohm	MCRO1MRTF1004
20	RESET SW1 SW2	3	Switch, Tact 6mm SMT, 160gf	Omron	B3S-1000
21	SW3	1	Switch, DPDT, SMT 300 mA*2 @ 6V	C&K Components	JS202011SCQN

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